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Ref: Case Docket No.: P1018

First Named Inventor: Michael L. Scherbarth

Serial Number: 09/755,480

Filing Date: 01/05/2001

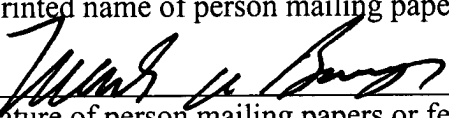
Title of Case: Lead-frame Design Modification to Facilitate Removal of Resist Tape from the Lead-frame

I hereby certify that the attached papers are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 C.F.R. 1.10 on the date indicated above and addressed to the Commissioner of Patents and Trademarks, Washington D.C. 20231

1. Response B.
2. RCE transmittal.
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Art Unit 2827  
Examiner David A. Zarneke

In Re: Michael L. Scherbarth et al.  
Case: P1018  
Serial No.: 09/755,480  
Filed: January 5, 2001  
Subject: Lead-frame Design Modification to Facilitate  
Removal of Resist Tape from the Lead-frame

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To: The Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Dear Sir;

**Response B**

All of the claims standing for examination are reproduced below. There are no amendments to the claims herein made in the present response.

1. A lead frame apparatus for holding IC packages during IC package processing comprising:

a substantially flat thin strip of conductive material having substantially parallel sides and square ends forming the lead frame apparatus;

a strip of adhesive material adhered to one surface of lead frame apparatus, the overall dimensions of the strip substantially the same as the overall dimensions of the lead frame apparatus;

a plurality of die-attach pads arranged on the non-adhesive surface of the lead frame apparatus, the pads for receiving IC packages for